

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Adrian E. Ong
Assignee: Inapac Technology, Inc.
Title: LAYOUT AND USE OF BOND PADS AND PROBE PADS FOR
TESTING OF INTEGRATED CIRCUITS DEVICES
Serial No.: Please assign Filing Date: Herewith
Examiner: Unknown Group Art Unit: Unknown
Docket No.: M-9433 US

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COMMISSIONER FOR PATENTS
Washington, D.C. 20231

San Francisco, California
November 15, 2001

**INFORMATION DISCLOSURE STATEMENT
UNDER 37 CFR § 1.97(b)**

Dear Sir:

Pursuant to 37 C.F.R. § 1.56, § 1.97 and § 1.98, the documents listed on the accompanying form PTO-1449 are called to the attention of the Examiner for the above patent application. Copies of these documents are enclosed.

Citation of these documents shall not be construed as:

1. an admission that the documents are necessarily prior art with respect to the instant invention;
2. a representation that a search has been made, other than as described above; or
3. an admission that the information cited herein is, or is considered to be, material to patentability as defined in § 1.56(b).

EXPRESS MAIL LABEL NO:

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Respectfully submitted,

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